

### **CLAIM AMENDMENTS**

Claims 1 -7 (cancelled)

Claim 8 (new) Dip soldering apparatus comprising:

a reservoir for molten solder and

an elongate plate provided in the reservoir and positioned at a surface of the molten solder into which surface component leads are to be dipped, the plate having an upwardly facing edge and side surfaces extending downwards from the plate edge, the plate being positioned and dimensioned so that adjacent component leads to be soldered pass to each side of the plate edge and the plate surface being of a material which is wetted by the molten solder.

Claim 9 (new) Dip soldering apparatus comprising a nozzle having an outlet through which solder is flowed in use, leads to be soldered being dipped into the solder surface at the nozzle outlet, wherein the nozzle includes a member provided at the nozzle outlet and having a surface which is wetted by the solder, the surface being positioned so as to be straddled by two adjacent leads of a component to be soldered.

Claim 10 (new) Apparatus as claimed in claim 9, wherein the member is below the level of the solder surface as the solder flows through the nozzle outlet.

Claim 11 (new) Apparatus as claimed in claim 9, wherein the member is movable relative to the solder surface.

Claim 12 (new) Apparatus as claimed in claim in claim 9, wherein the member is positioned so as to project through the solder surface as the leads are withdrawn from the solder.

Claim 13 (new) Apparatus as claimed in claim 12, wherein means is provided to lower the solder surface to effect withdrawal of the leads from the solder.

Claim 14 (new) Apparatus as claimed in claim 9, wherein the member is an elongated plate having an upwardly facing edge.

Claim 15 (new) Apparatus as claimed in claim 9, wherein the member has a honeycomb structure.